Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1.(Currently Amended) A device for controlling one or more memory modules, the device comprising:

a first memory module with a temperature sensor ~~for detecting~~ configured to detect the temperature of the first memory module, the temperature sensor being arranged in the first memory module;

a second memory module with a second temperature sensor ~~for detecting~~ configured to detect the temperature of the second memory module, the second temperature sensor being arranged in the second memory module;

a means for determining a highest temperature among the detected temperatures, the respective temperature of the first and second memory modules being passed to the means for determining the highest temperature; and

a memory control module~~, the memory control module being~~ connected to the first and second memory modules via the means for determining the highest temperature, the highest temperature being passed to the control module and the memory control module being ~~designed such that an adaptation operation is initiated, if~~ configured to initiate an adaptation operation, in the event that the determined highest temperature exceeds a predetermined value.

2. (Currently Amended) The device as claimed in claim 1, wherein:

the first and second memory modules ~~having~~ comprise pulse width coders~~, the pulse width coders generating~~ configured to generate pulse-width-coded temperature signals, the signals being connected upstream of the means for determining the highest temperature[[,]] ; and

the means for determining the highest temperature ~~having~~ comprises a wired OR circuit ~~, the circuit combining~~ configured to combine the pulse-width-coded temperature signals.

3. (Currently Amended) A method for controlling one or more memory modules, the method comprising:

transmitting temperature signals from [[a]] first and second memory modules to ~~the~~ a means for determining a highest temperature, the temperature signals corresponding to respective temperatures of the memory modules;

determining [[the]] a highest temperature among the memory modules from the transmitted temperature signals;

communicating the temperature signal corresponding to the highest temperature to a memory control module;

evaluating the temperature signal corresponding to the highest temperature; and

initiating an adaptation operation, [[if]] in the event that the temperature of the highest memory module exceeds a predetermined value.

4. (Original) The method as claimed in claim 3, wherein a number of commands per unit time transmitted to the first and second memory modules is reduced by the adaptation operation.

5. (Currently Amended) The method as claimed in claim 3, wherein ~~the temperature in the first and second memory modules is lowered~~ a cooling unit is activated by the adaptation operation ~~activating a cooling unit is activated~~.

6. (Original) The method as claimed in claim 3, wherein a number of memory refreshes per unit time is increased by the adaptation operation.

7. (Original) The method as claimed in claim 3, wherein one of the memory modules is deactivated in a predetermined manner by the adaptation operation.

8. (Original) The method as claimed in claim 3, wherein a system is ramped down in a predetermined manner by the adaptation operation.

9. (Original) The method as claimed in claim 3, wherein the temperature is binary-coded.

10. (Original) The method as claimed in claim 3, wherein the temperature is converted into a frequency-coded temperature signal.

11. (Original) The method as claimed in claim 3, wherein the temperature is converted into a pulse-width-coded temperature signal.

12. (Original) The method as claimed in claim 3, wherein the temperature is converted into an analog temperature signal.

13. (Currently Amended) A device for controlling one or more memory modules, the device comprising:

a first memory module with a temperature sensor ~~for detecting~~ configured to detect the temperature of the first memory module, the temperature sensor being arranged in the first memory module;

a second memory module with a second temperature sensor ~~for detecting~~ configured to detect the temperature of the second memory module, the second temperature sensor being arranged in the second memory module;

a measurer ~~for determining~~ configured to determine a highest temperature of the detected temperatures, the respective temperature of the first and second memory modules being passed to the means for determining the highest temperature; and

a memory control module~~, the memory control module being~~ connected to the first and second memory modules via the measurer, the highest temperature being supplied to the control

module and the memory control module being ~~designed such that~~ configured to initiate an adaptation operation ~~is initiated, if~~ , in the event that the determined highest temperature ~~exceeds~~ exceeding a predetermined value.

14. (Currently Amended) The device as claimed in claim 13, wherein:

the first and second memory modules ~~having~~ comprise pulse width coders~~, the pulse width coders generating~~ configured to generate pulse-width-coded temperature signals, the signals being connected upstream of the measurer[[,]] ; and

the measurer ~~having~~ comprises a wired OR circuit~~, the circuit combining~~ configured to combine the pulse-width-coded temperature signals.

15. (Currently Amended) A method for controlling one or more memory modules, the method comprising:

transmitting temperature signals from [[a]] first and second memory modules to ~~the measurer for determining~~ a measurer configured to determine a highest temperature, the temperature signals corresponding to respective temperatures of the memory modules;

determining [[the]] a highest temperature among the memory modules from the transmitted temperature signals;

communicating the temperature signal corresponding to the highest temperature to a memory control module;

evaluating the temperature signal corresponding to the highest temperature; and

initiating an adaptation operation, [[if]] in the event that the determined temperature of the highest memory module exceeds a predetermined value.

16. (Original) The method as claimed in claim 15, wherein a number of commands per unit time transmitted to the first and second memory modules is reduced by the adaptation operation.

17. (Currently Amended) The method as claimed in claim 15, wherein ~~the temperature in the first and second memory modules is lowered~~ a cooling unit is activated by the adaptation operation ~~activating a cooling unit is activated~~.

18. (Original) The method as claimed in claim 15, wherein a number of memory refreshes per unit time is increased by the adaptation operation.

19. (Original) The method as claimed in claim 15, wherein one of the memory modules is deactivated in a predetermined manner by the adaptation operation.

20. (Original) The method as claimed in claim 15, wherein a system is ramped down in a predetermined manner by the adaptation operation.

21. (Original) The method as claimed in claim 15, wherein the temperature is binary-coded.

22. (Original) The method as claimed in claim 15, wherein the temperature is converted into a frequency-coded temperature signal.

23. (Original) The method as claimed in claim 15, wherein the temperature is converted into a pulse-width-coded temperature signal.

24.(Original) The method as claimed in claim 15, wherein the temperature is converted into an analog temperature signal.